

SOT411-2

plastic DIL-bent-SIL power package; 23 leads (lead length 12 mm)

8 February 2016

Package information

1. Package summary

Terminal position code	Z (zig-zag)
Package type descriptive code	DBS23P
Package type industry code	DBS23P
Package style descriptive code	DBS (DIL-bent-SIL)
Package style suffix code	P (power)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	24-4-2002

Table 1. Package summary

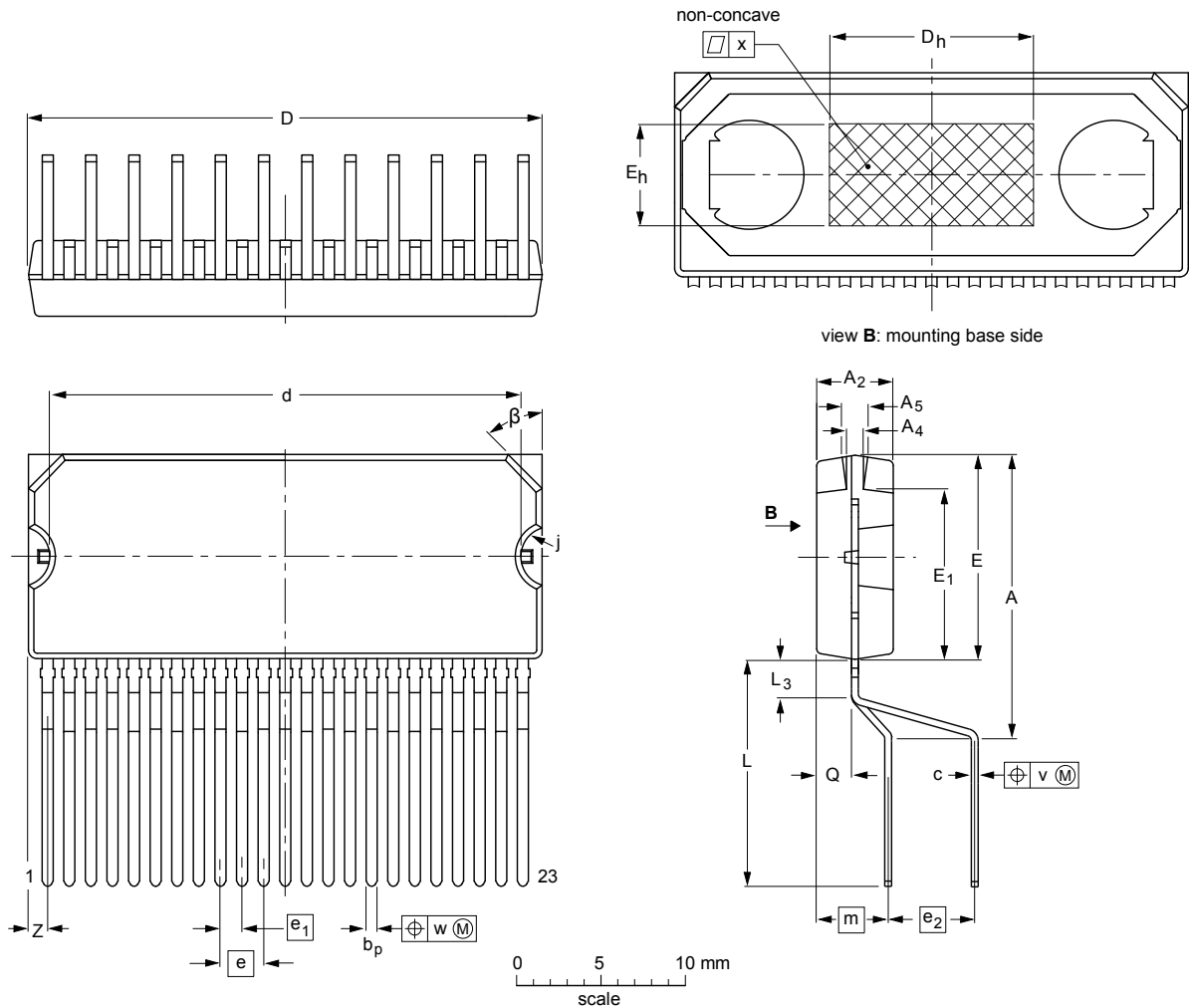
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	29.9	-	30.15	30.4	mm
E	package width	11.8	-	12	12.2	mm
A	seated height	15.5	-	16.25	17	mm
A ₂	package height	4.3	-	4.45	4.6	mm
n ₂	actual quantity of termination	-	-	23	-	



2. Package outline

DBS23P: plastic DIL-bent-SIL power package; 23 leads (lead length 12 mm)

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DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₂	A ₄	A ₅	b _p	c	D ⁽¹⁾	d	D _h	E ⁽¹⁾	e	e ₁	e ₂	E _h	E ₁	j	L	L ₃	m	Q	v	w	x	β	z ⁽¹⁾
mm	17.0 15.5	4.6 4.3	1.15 0.85	1.65 1.35	0.75 0.60	0.55 0.35	30.4 29.9	28.0 27.5	12	12.2 11.8	2.54	1.27	5.08	6	10.15 9.85	1.85 1.65	12.4 11.0	2.4 1.6	4.3	2.1 1.8	0.8	0.25	0.03	45°	1.43 0.78

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT411-2						98-02-18 02-04-24

Fig. 1. Package outline DBS23P (SOT411-2)

3. Legal information

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